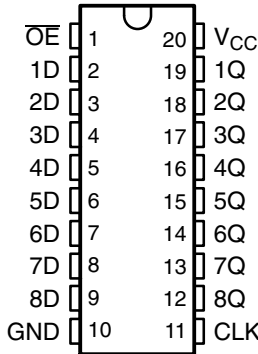


# SN54ABT574, SN74ABT574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

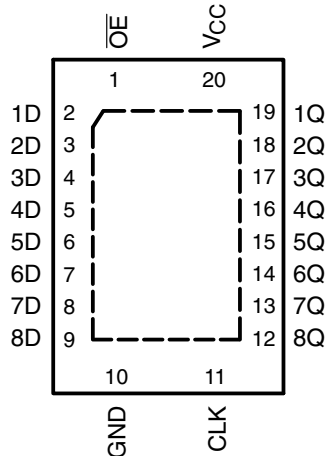
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- Typical  $V_{OLP}$  (Output Ground Bounce)  $<1$  V at  $V_{CC} = 5$  V,  $T_A = 25^\circ\text{C}$
- High-Drive Outputs ( $-32\text{-mA } I_{OH}$ ,  $64\text{-mA } I_{OL}$ )
- $I_{off}$  Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)

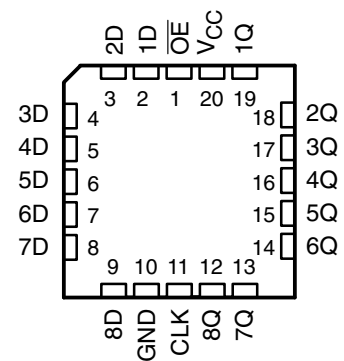
SN54ABT574 . . . J OR W PACKAGE  
SN74ABT574A . . . DB, DW, N, NS,  
OR PW PACKAGE  
(TOP VIEW)



SN74ABT574A . . . RGY PACKAGE  
(TOP VIEW)



SN54ABT574 . . . FK PACKAGE  
(TOP VIEW)



## description/ordering information

These 8-bit flip-flops feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

## ORDERING INFORMATION

$T_A$	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP – N	Tube	SN74ABT574AN	SN74ABT574AN
	QFN – RGY	Tape and reel	SN74ABT574ARGYR	AB574A
	SOIC – DW	Tube	SN74ABT574ADW	ABT574A
		Tape and reel	SN74ABT574ADWR	
	SOP – NS	Tape and reel	SN74ABT574ANSR	ABT574A
	SSOP – DB	Tape and reel	SN74ABT574ADBR	AB574A
	TSSOP – PW	Tube	SN74ABT574APW	AB574A
		Tape and reel	SN74ABT574APWR	
-55°C to 125°C	VFBGA – GQN	Tape and reel	SN74ABT574AGQNR	AB574A
	VFBGA – ZQN (Pb-free)		SN74ABT574AZQNR	
	CDIP – J	Tube	SNJ54ABT574J	SNJ54ABT574J
	CFP – W	Tube	SNJ54ABT574W	SNJ54ABT574W
	LCCC – FK	Tube	SNJ54ABT574FK	SNJ54ABT574FK

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS  
INSTRUMENTS**

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On products compliant to MIL-PRF-38535, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

# SN54ABT574, SN74ABT574A OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS WITH 3-STATE OUTPUTS

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## description/ordering information (continued)

The eight flip-flops of the SN54ABT574 and SN74ABT574A are edge-triggered D-type flip-flops. On the positive transition of the clock (CLK) input, the Q outputs are set to the logic levels set up at the data (D) inputs.

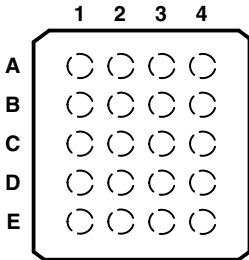
A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

$\overline{OE}$  does not affect the internal operations of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

SN74ABT574A . . . GQN OR ZQN PACKAGE  
(TOP VIEW)



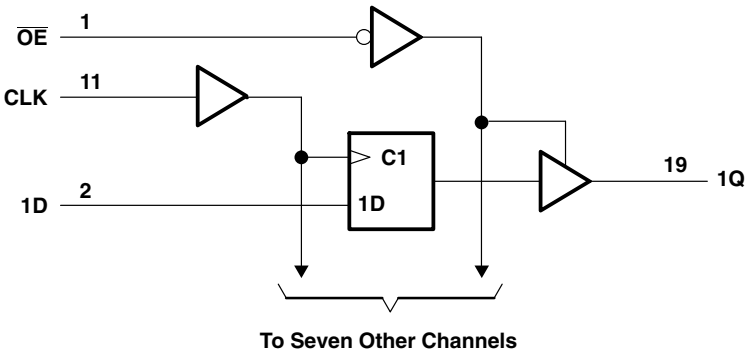
## terminal assignments

	1	2	3	4
A	1D	$\overline{OE}$	$V_{CC}$	1Q
B	3D	3Q	2D	2Q
C	5D	4D	5Q	4Q
D	7D	7Q	6D	6Q
E	GND	8D	CLK	8Q

FUNCTION TABLE  
(each flip-flop)

INPUTS			OUTPUT Q
$\overline{OE}$	CLK	D	
L	$\uparrow$	H	H
L	$\uparrow$	L	L
L	H or L	X	$Q_0$
H	X	X	Z

## logic diagram (positive logic)



Pin numbers shown are for the DB, DW, FK, J, N, NS, PW, RGY, and W packages.

# SN54ABT574, SN74ABT574A

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$	–0.5 V to 7 V
Input voltage range, $V_I$ (see Note 1)	–0.5 V to 7 V
Voltage range applied to any output in the high or power-off state, $V_O$	–0.5 V to 5.5 V
Current into any output in the low state, $I_O$ : SN54ABT574	96 mA
SN74ABT574A	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, $I_{OK}$ ( $V_O < 0$ )	–50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 2): DB package	70°C/W
(see Note 2): DW package	58°C/W
(see Note 2): GQN/ZQN package	78°C/W
(see Note 2): N package	69°C/W
(see Note 2): NS package	60°C/W
(see Note 2): PW package	83°C/W
(see Note 3): RGY package	37°C/W
Storage temperature range, $T_{stg}$	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.  
3. The package thermal impedance is calculated in accordance with JESD 51-5.

#### recommended operating conditions (see Note 4)

		SN54ABT574		SN74ABT574A		UNIT
		MIN	MAX	MIN	MAX	
$V_{CC}$	Supply voltage	4.5	5.5	4.5	5.5	V
$V_{IH}$	High-level input voltage	2		2		V
$V_{IL}$	Low-level input voltage		0.8		0.8	V
$V_I$	Input voltage	0	$V_{CC}$	0	$V_{CC}$	V
$I_{OH}$	High-level output current		–24		–32	mA
$I_{OL}$	Low-level output current		48		64	mA
$\Delta t/\Delta v$	Input transition rise or fall rate	Outputs enabled		5	5	ns/V
$T_A$	Operating free-air temperature	–55	125	–40	85	°C

NOTE 4: All unused inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



# SN54ABT574, SN74ABT574A

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	$T_A = 25^\circ\text{C}$			SN54ABT574		SN74ABT574A		UNIT
		MIN	TYP†	MAX	MIN	MAX	MIN	MAX	
$V_{IK}$	$V_{CC} = 4.5\text{ V}$ , $I_I = -18\text{ mA}$			-1.2		-1.2		-1.2	V
$V_{OH}$	$V_{CC} = 4.5\text{ V}$ , $I_{OH} = -3\text{ mA}$	2.5			2.5		2.5		V
	$V_{CC} = 5\text{ V}$ , $I_{OH} = -3\text{ mA}$	3			3		3		
	$V_{CC} = 4.5\text{ V}$	$I_{OH} = -24\text{ mA}$	2		2				
		$I_{OH} = -32\text{ mA}$	2*				2		
$V_{OL}$	$V_{CC} = 4.5\text{ V}$	$I_{OL} = 48\text{ mA}$		0.55		0.55			V
		$I_{OL} = 64\text{ mA}$		0.55*				0.55	
$V_{hys}$			100						mV
$I_I$	$V_{CC} = 5.5\text{ V}$ , $V_I = V_{CC}$ or GND			$\pm 1$		$\pm 1$		$\pm 1$	$\mu\text{A}$
$I_{OZH}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.7\text{ V}$			$10^\ddagger$		$10^\ddagger$		$10^\ddagger$	$\mu\text{A}$
$I_{OZL}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 0.5\text{ V}$			$-10^\ddagger$		$-10^\ddagger$		$-10^\ddagger$	$\mu\text{A}$
$I_{off}$	$V_{CC} = 0$ , $V_I$ or $V_O \leq 4.5\text{ V}$			$\pm 100$		$\pm 500$		$\pm 100$	$\mu\text{A}$
$I_{CEX}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 5.5\text{ V}$			50		50		50	$\mu\text{A}$
$I_O^{\S}$	$V_{CC} = 5.5\text{ V}$ , $V_O = 2.5\text{ V}$	-50	-100	-180	-50	-180	-50	-180	mA
$I_{CC}$	$V_{CC} = 5.5\text{ V}$ , $I_O = 0$ , $V_I = V_{CC}$ or GND	Outputs high		1 250		250		250	$\mu\text{A}$
		Outputs low		24 30		30		30	mA
		Outputs disabled		0.5 250		250		250	$\mu\text{A}$
$\Delta I_{CC}^{\parallel}$	$V_{CC} = 5.5\text{ V}$ , One input at 3.4 V, Other inputs at $V_{CC}$ or GND			1.5		1.5		1.5	mA
$C_i$	$V_I = 2.5\text{ V}$ or $0.5\text{ V}$			3.5					pF
$C_o$	$V_O = 2.5\text{ V}$ or $0.5\text{ V}$			6.5					pF

\* On products compliant to MIL-PRF-38535, this parameter does not apply.

† All typical values are at  $V_{CC} = 5\text{ V}$ .

‡ This data-sheet limit may vary among suppliers.

§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

¶ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than  $V_{CC}$  or GND.

**timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)**

			SN54ABT574		UNIT		
			V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN	MAX
			MIN	MAX			
f <sub>clock</sub>	Clock frequency		150	150	MHz		
t <sub>w</sub>	Pulse duration, CLK high or low		3.3	3.3	ns		
t <sub>su</sub>	Setup time, data before CLK↑	High	1.5	1.5	ns		
		Low	2	2			
t <sub>h</sub>	Hold time, data after CLK↑	High or low	2	2	ns		



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# SN54ABT574, SN74ABT574A

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

### WITH 3-STATE OUTPUTS

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

			SN74ABT574A		UNIT
			$V_{CC} = 5\text{ V},$ $T_A = 25^{\circ}\text{C}$		
			MIN	MAX	
f <sub>clock</sub>	Clock frequency		150	150	MHz
t <sub>w</sub>	Pulse duration, CLK high or low		3.3	3.3	ns
t <sub>su</sub>	Setup time, data before CLK↑	High	1	1	ns
		Low	1.5	1.5	
t <sub>h</sub>	Hold time, data after CLK↑	High or low	1.8†	1.8†	ns

$\dagger$  This data-sheet limit may vary among suppliers.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54ABT574				UNIT	
			V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN		MAX
			MIN	TYP	MAX			
f <sub>max</sub>			150	200		150	MHz	
t <sub>PLH</sub>	CLK	Q	2.2	3.9	6.2	2.2	7	ns
t <sub>PHL</sub>			3	4.8	7	3	7.4	
t <sub>PZH</sub>	OE	Q	1	3.3	5	1	5.8	ns
t <sub>PZL</sub>			2.5	4.7	5.9	2.5	7.2	
t <sub>PHZ</sub>	OE	Q	2.4	4.9	6.2	2.4	7.2	ns
t <sub>PLZ</sub>			2	4	5.8	2	6.9	

switching characteristics over recommended ranges of supply voltage and operating free-air temperature,  $C_L = 50\text{ pF}$  (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN74ABT574A				UNIT	
			V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			MIN		MAX
			MIN	TYP	MAX			
f <sub>max</sub>			150	200		150	MHz	
t <sub>PLH</sub>	CLK	Q	2.2	3.9	6.2	2.2	6.8	ns
t <sub>PHL</sub>			3	4.8	6.6	3	7.1	
t <sub>PZH</sub>	OE	Q	1	3.3	4.3	1	5.1	ns
t <sub>PZL</sub>			2.1†	4.7	5.9	2.1†	6.7	
t <sub>PHZ</sub>	OE	Q	2.4	4.9	6.2	2.4	7	ns
t <sub>PLZ</sub>			2	4	5.8	2	6.5	

$\dagger$  This data-sheet limit may vary among suppliers.

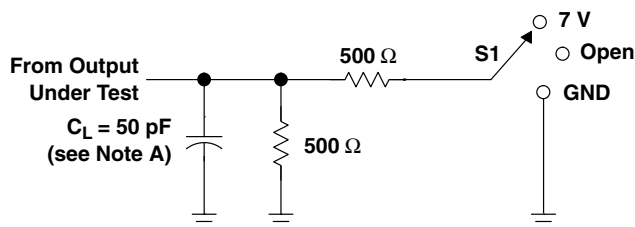
# SN54ABT574, SN74ABT574A

## OCTAL EDGE-TRIGGERED D-TYPE FLIP-FLOPS

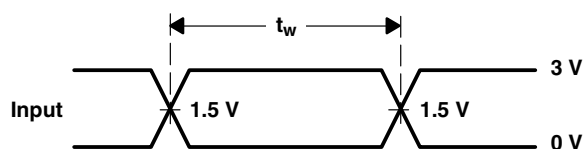
### WITH 3-STATE OUTPUTS

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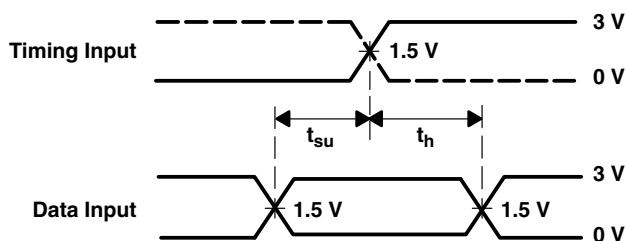
#### PARAMETER MEASUREMENT INFORMATION



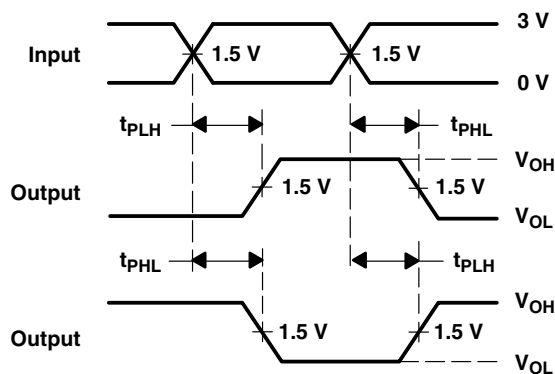
LOAD CIRCUIT



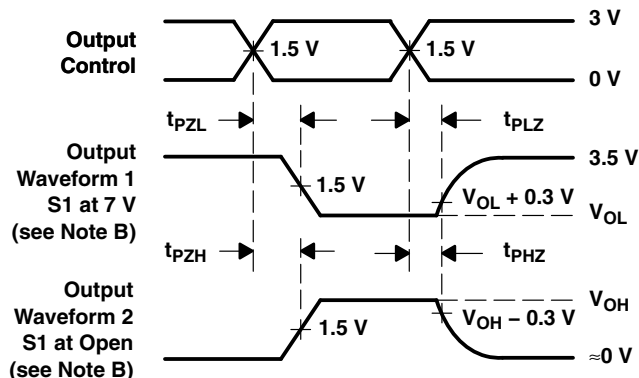
VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES  
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES  
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">5962-9322001Q2A</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9322001Q2A SNJ54ABT 574FK
<a href="#">5962-9322001QRA</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9322001QR A SNJ54ABT574J
<a href="#">5962-9322001QSA</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9322001QS A SNJ54ABT574W
<a href="#">SN74ABT574ADBR</a>	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
SN74ABT574ADBR.B	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
SN74ABT574ADBRG4	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
SN74ABT574ADBRG4.B	Active	Production	SSOP (DB)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
<a href="#">SN74ABT574ADW</a>	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
SN74ABT574ADW.B	Active	Production	SOIC (DW)   20	25   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
<a href="#">SN74ABT574ADWR</a>	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
SN74ABT574ADWR.B	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
SN74ABT574ADWRE4	Active	Production	SOIC (DW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
<a href="#">SN74ABT574AN</a>	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT574AN
SN74ABT574AN.B	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT574AN
SN74ABT574ANE4	Active	Production	PDIP (N)   20	20   TUBE	Yes	NIPDAU	N/A for Pkg Type	-40 to 85	SN74ABT574AN
<a href="#">SN74ABT574ANSR</a>	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
SN74ABT574ANSR.B	Active	Production	SOP (NS)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ABT574A
<a href="#">SN74ABT574APW</a>	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
SN74ABT574APW.B	Active	Production	TSSOP (PW)   20	70   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
<a href="#">SN74ABT574APWR</a>	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
SN74ABT574APWR.B	Active	Production	TSSOP (PW)   20	2000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	AB574A
<a href="#">SNJ54ABT574FK</a>	Active	Production	LCCC (FK)   20	55   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962- 9322001Q2A SNJ54ABT 574FK

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">SNJ54ABT574J</a>	Active	Production	CDIP (J)   20	20   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9322001QR A SNJ54ABT574J
<a href="#">SNJ54ABT574W</a>	Active	Production	CFP (W)   20	25   TUBE	No	SNPB	N/A for Pkg Type	-55 to 125	5962-9322001QS A SNJ54ABT574W

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ABT574ADBR	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT574ADBRG4	SSOP	DB	20	2000	330.0	16.4	8.2	7.5	2.5	12.0	16.0	Q1
SN74ABT574ADWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
SN74ABT574ANSR	SOP	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1
SN74ABT574APWR	TSSOP	PW	20	2000	330.0	16.4	6.95	7.0	1.4	8.0	16.0	Q1

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ABT574ADBR	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT574ADBRG4	SSOP	DB	20	2000	353.0	353.0	32.0
SN74ABT574ADWR	SOIC	DW	20	2000	356.0	356.0	45.0
SN74ABT574ANSR	SOP	NS	20	2000	356.0	356.0	45.0
SN74ABT574APWR	TSSOP	PW	20	2000	353.0	353.0	32.0

## TUBE



\*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
5962-9322001Q2A	FK	LCCC	20	55	506.98	12.06	2030	NA
5962-9322001QSA	W	CFP	20	25	506.98	26.16	6220	NA
SN74ABT574ADW	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT574ADW.B	DW	SOIC	20	25	507	12.83	5080	6.6
SN74ABT574AN	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT574AN.B	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT574ANE4	N	PDIP	20	20	506	13.97	11230	4.32
SN74ABT574APW	PW	TSSOP	20	70	530	10.2	3600	3.5
SN74ABT574APW.B	PW	TSSOP	20	70	530	10.2	3600	3.5
SNJ54ABT574FK	FK	LCCC	20	55	506.98	12.06	2030	NA
SNJ54ABT574W	W	CFP	20	25	506.98	26.16	6220	NA

J (R-GDIP-T\*\*)

14 LEADS SHOWN

# CERAMIC DUAL IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package is hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
  - E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

## GENERIC PACKAGE VIEW

**FK 20**

**LCCC - 2.03 mm max height**

8.89 x 8.89, 1.27 mm pitch

LEADLESS CERAMIC CHIP CARRIER

This image is a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.



4229370VA\

N (R-PDIP-T\*\*)

16 PINS SHOWN

## PLASTIC DUAL-IN-LINE PACKAGE



PINS ** DIM	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS-001 VARIATION	AA	BB	AC	AD



4040049/E 12/2002

NOTES:

- A. All linear dimensions are in inches (millimeters).  
B. This drawing is subject to change without notice.
-  Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).  
 The 20 pin end lead shoulder width is a vendor option, either half or full width.

**DW0020A****PACKAGE OUTLINE****SOIC - 2.65 mm max height**

SOIC



4220724/A 05/2016

**NOTES:**

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.

**DW0020A**

### SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE  
SCALE:6X



## SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.  
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## EXAMPLE STENCIL DESIGN

DW0020A

SOIC - 2.65 mm max height

SOIC

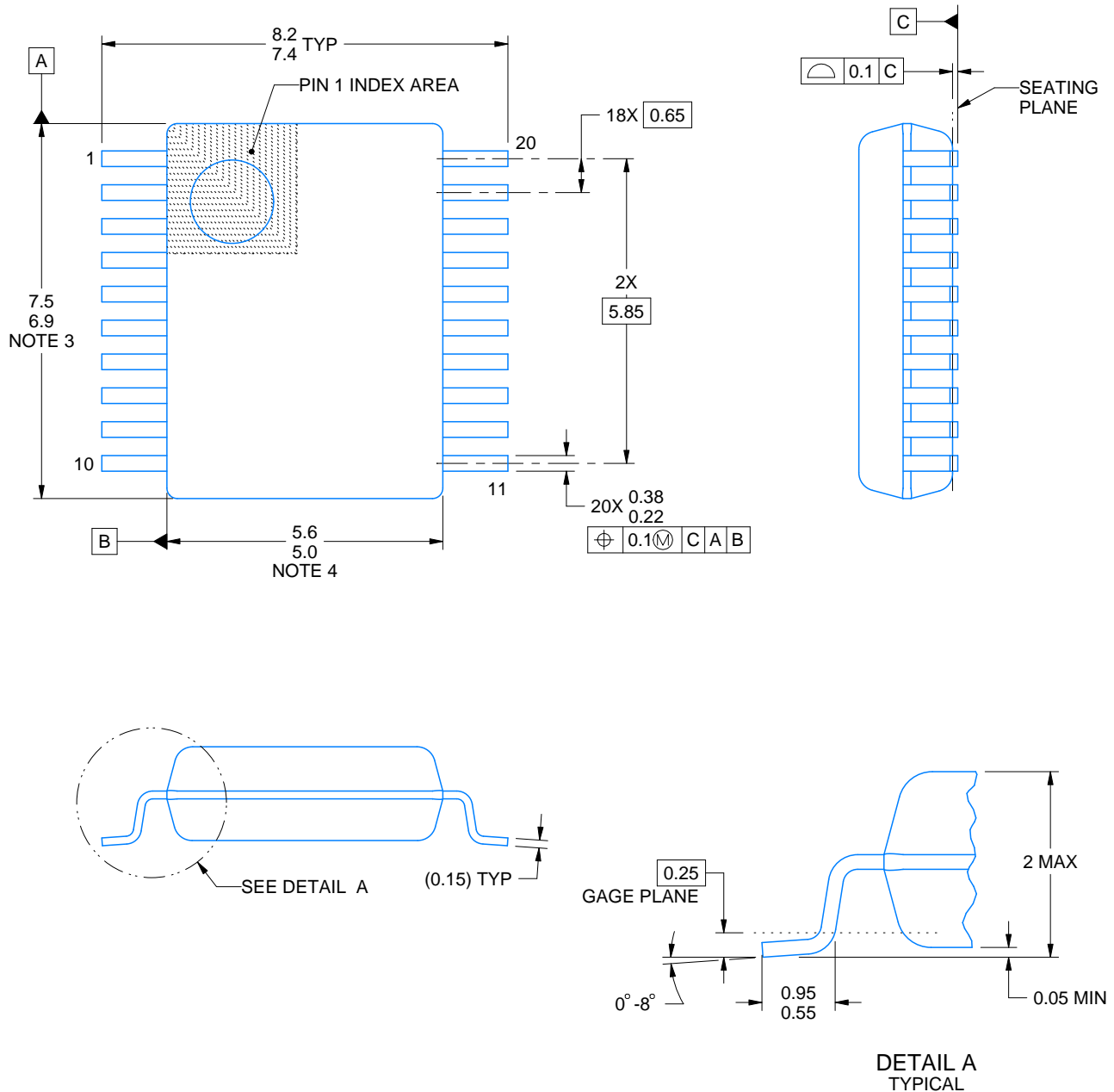
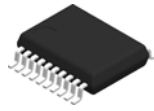


SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.



4214851/B 08/2019

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.

# EXAMPLE BOARD LAYOUT

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

## EXAMPLE STENCIL DESIGN

DB0020A

SSOP - 2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4214851/B 08/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

# MECHANICAL DATA

NS (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

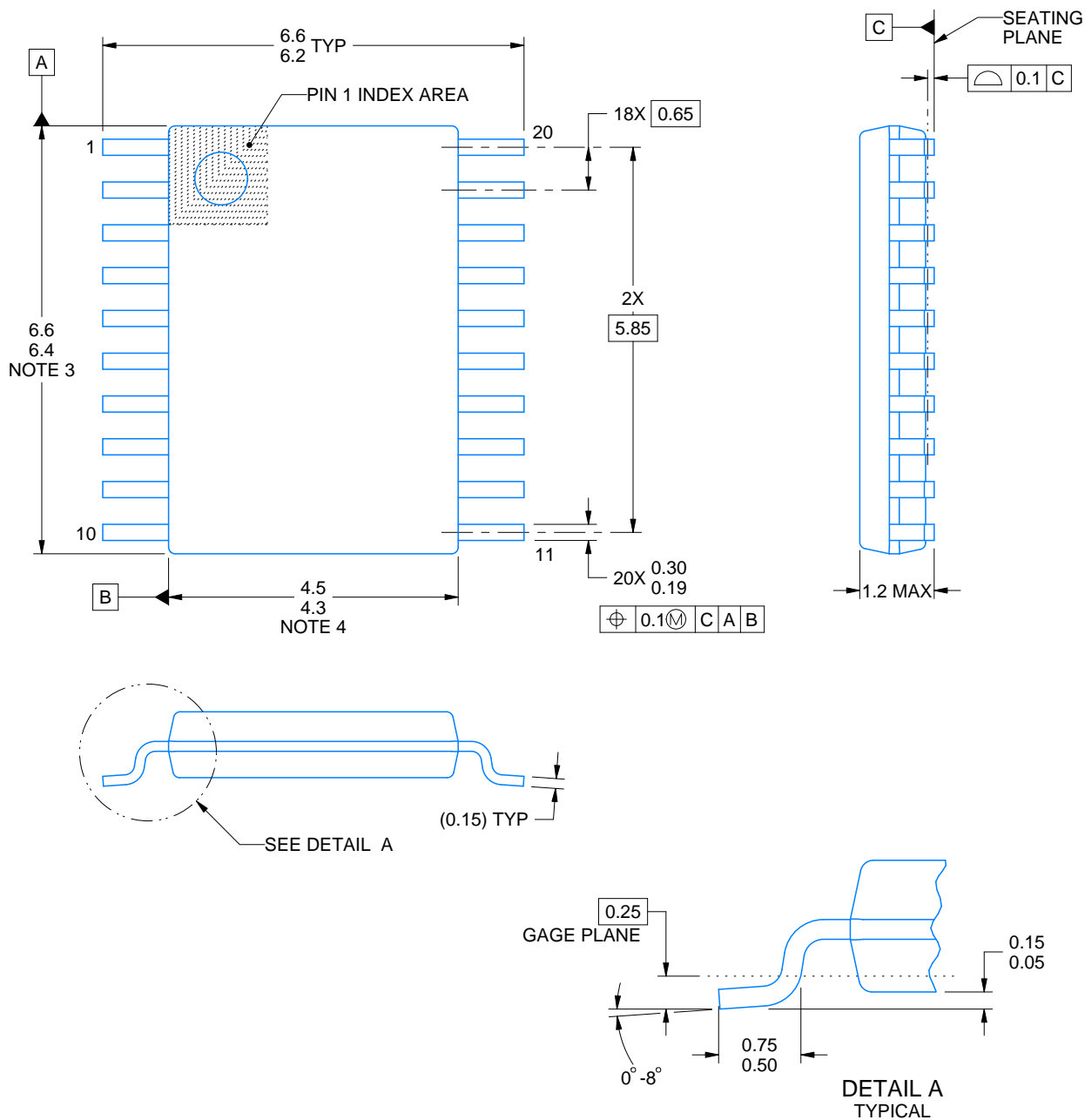
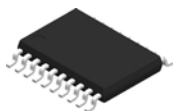
- NOTES:
- A. All linear dimensions are in millimeters.
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

W (R-GDFP-F20)

CERAMIC DUAL FLATPACK



- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. This package can be hermetically sealed with a ceramic lid using glass frit.
  - D. Index point is provided on cap for terminal identification only.
  - E. Falls within Mil-Std 1835 GDFP2-F20



4220206/A 02/2017

## NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

# EXAMPLE BOARD LAYOUT

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE  
EXPOSED METAL SHOWN  
SCALE: 10X



4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



## EXAMPLE STENCIL DESIGN

PW0020A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE  
BASED ON 0.125 mm THICK STENCIL  
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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